



## Description

### JMT P-channel Enhancement Mode Power MOSFET

#### Features

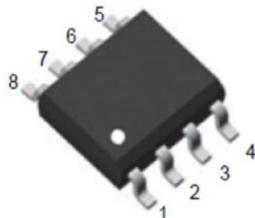
- $V_{DS} = -30V$ ,  $I_D = -15A$
- $R_{DS(ON)} < 9m\Omega$  @  $V_{GS} = -10V$
- $R_{DS(ON)} < 14m\Omega$  @  $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

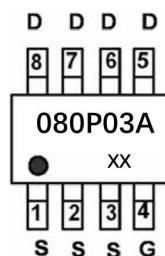
- PWM Applications
- Load Switch
- Power Management



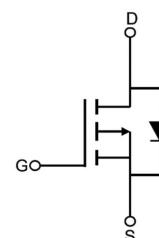
100% UIS TESTED!  
100%  $\Delta V_{ds}$  TESTED!



SOP-8 top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
080P03A	JMTP080P03A	TAPING	SOP-8	13inch	4000	48000

## Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		-30	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	-15	A
		$T_A = 100^\circ C$	-10	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		-60	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>		144	mJ
$P_D$	Power Dissipation	$T_A = 25^\circ C$	3	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		41.7	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

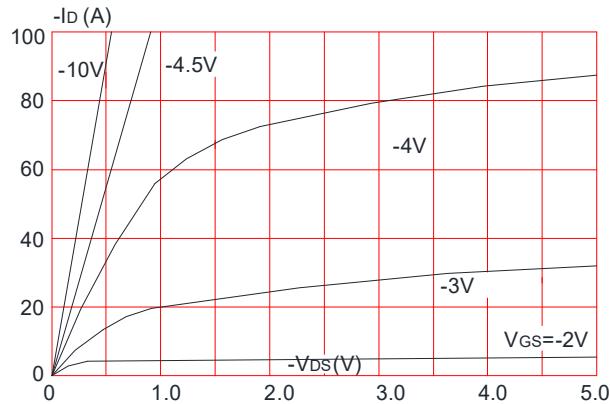
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D = -250\mu\text{A}$	-30	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = -30\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	-1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D = -250\mu\text{A}$	-1.0	-1.5	-2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS} = -10\text{V}$ , $I_D = -15\text{A}$	-	7	9	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}$ , $I_D = -10\text{A}$	-	10	14	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = -15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	4650	-	pF
$C_{oss}$	Output Capacitance		-	550	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	486	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = -15\text{V}$ , $I_D = -10\text{A}$ , $V_{GS} = -10\text{V}$	-	45	-	nC
$Q_{gs}$	Gate-Source Charge		-	8	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	12	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -15\text{V}$ , $I_D = -15\text{A}$ , $V_{GS} = -10\text{V}$ , $R_{\text{GEN}} = 2.5\Omega$	-	19	-	ns
$t_r$	Turn-on Rise Time		-	15	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	65	-	ns
$t_f$	Turn-off Fall Time		-	36	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	-15	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-60	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s = -15\text{A}$	-	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

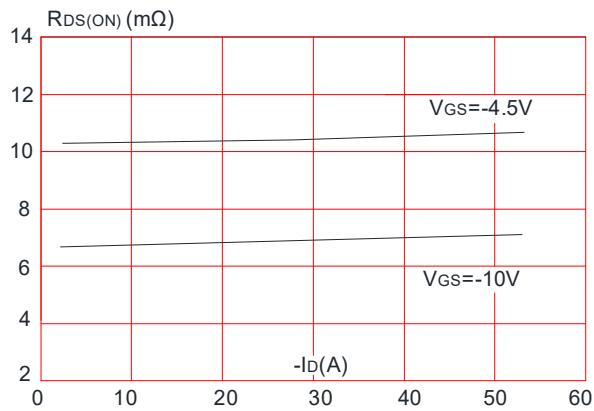
2.  $E_{AS}$  condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD} = -15\text{V}$ ,  $V_G = -10\text{V}$ ,  $R_G = 25\Omega$ ,  $L = 0.5\text{mH}$ ,  $I_{AS} = -24\text{A}$ 3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$

## Typical Performance Characteristics

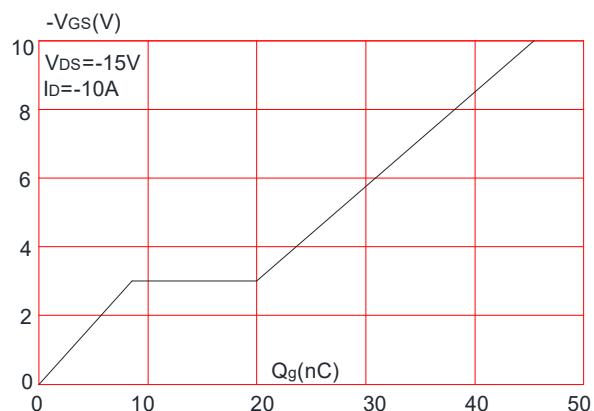
**Figure 1:** Output Characteristics



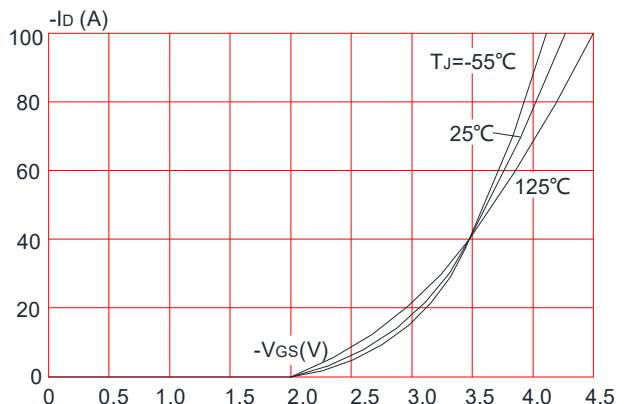
**Figure 3:** On-resistance vs. Drain Current



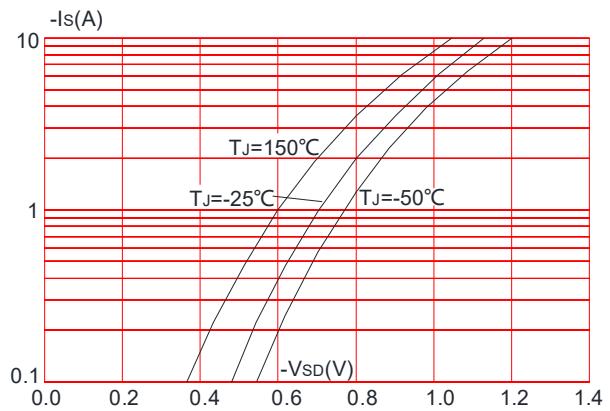
**Figure 5: Gate Charge Characteristics**



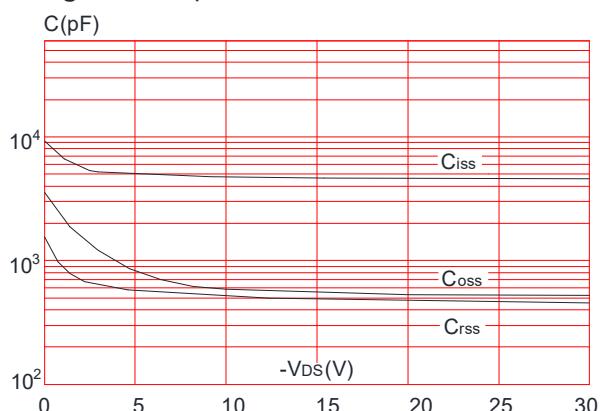
**Figure 2:** Typical Transfer Characteristics



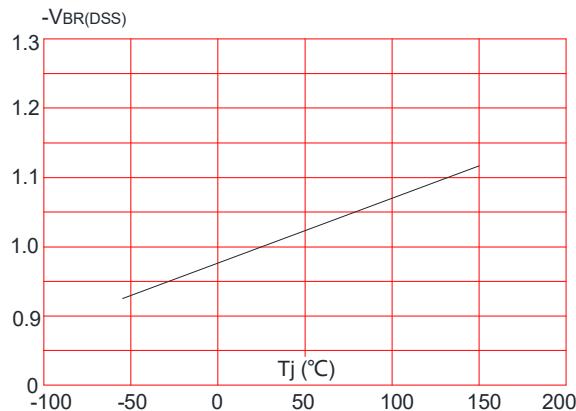
**Figure 4:** Body Diode Characteristics



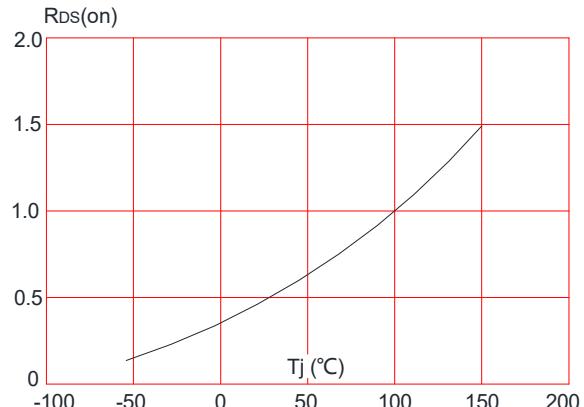
**Figure 6: Capacitance Characteristics**



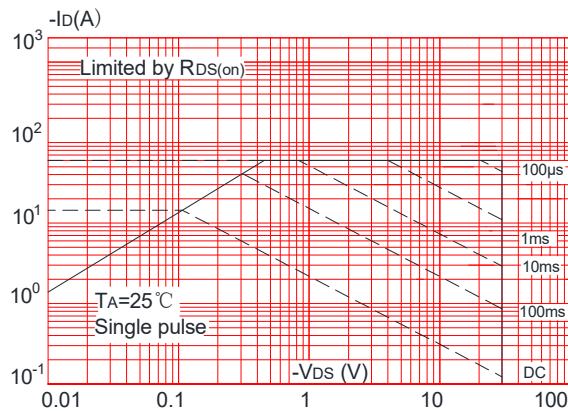
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



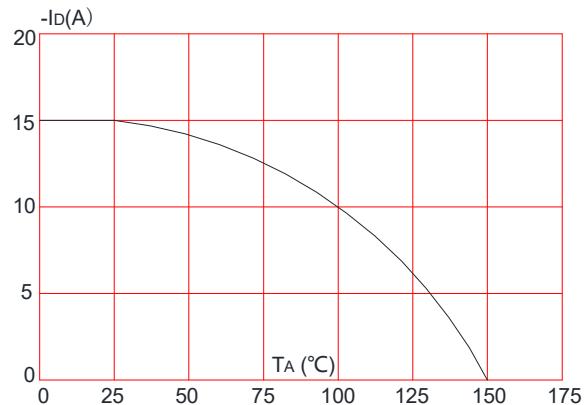
**Figure 8:** Normalized on Resistance vs. Junction Temperature



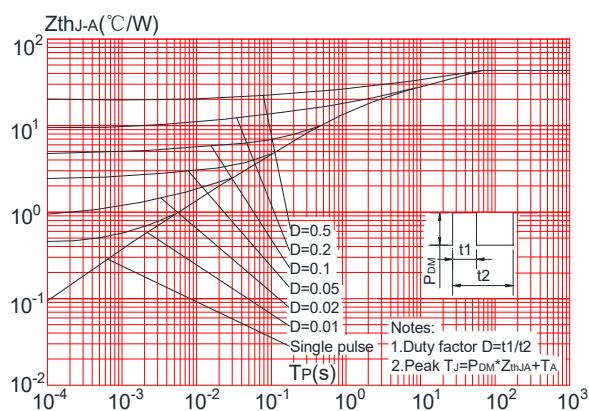
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature

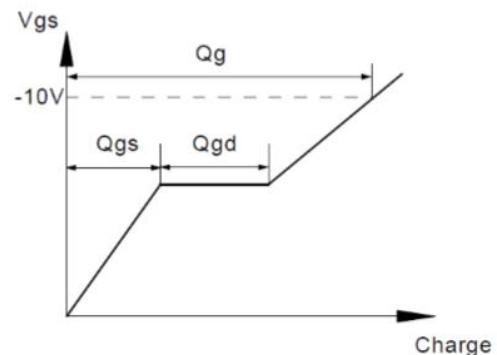
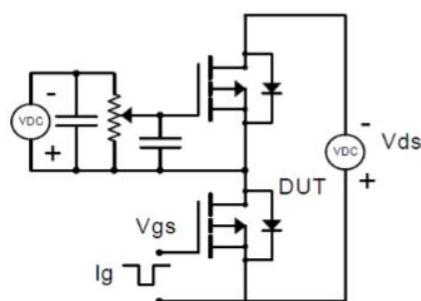


**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

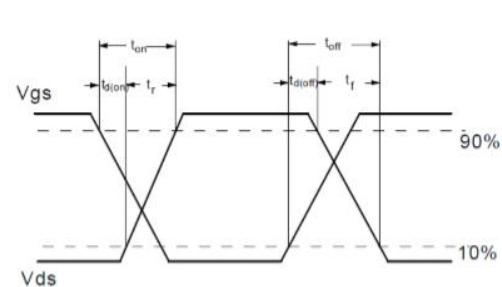
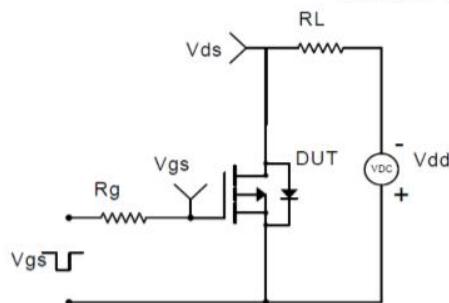


## Test Circuit

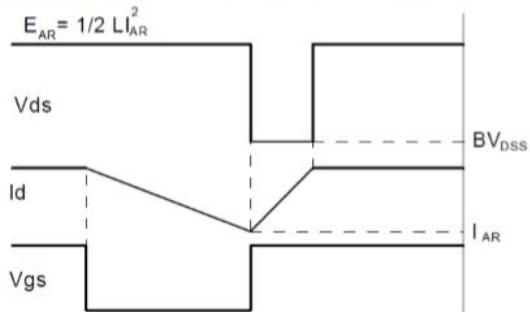
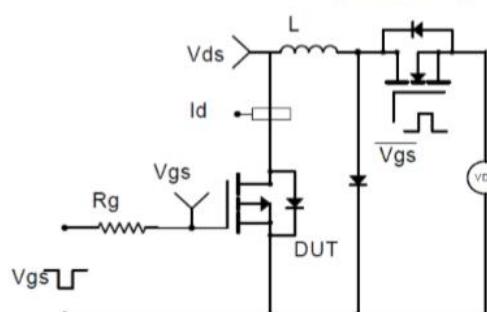
Gate Charge Test Circuit & Waveform



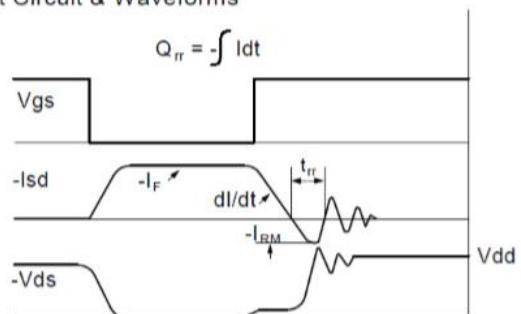
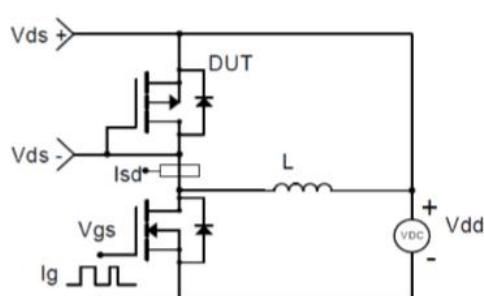
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

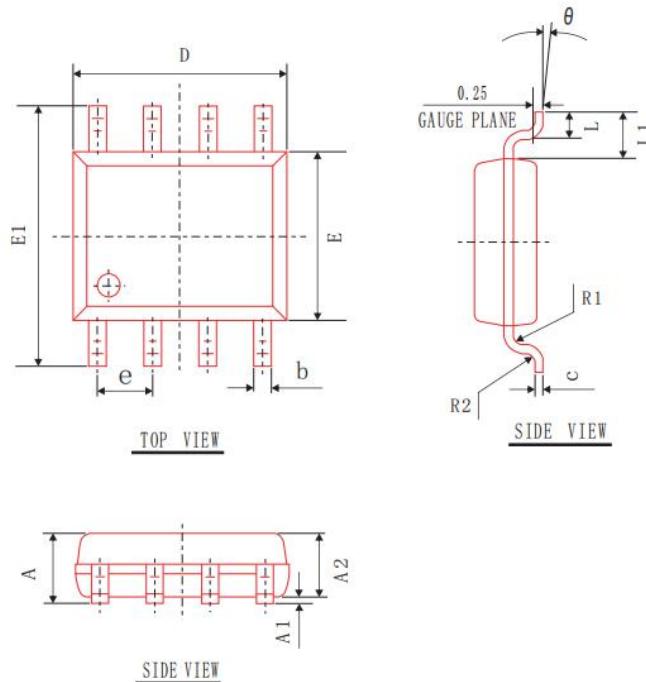


Diode Recovery Test Circuit & Waveforms





## Package Mechanical Data- SOP-8

COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
θ	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		

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